











SBOS539A - DECEMBER 2010-REVISED APRIL 2016

INA203-Q1

# INA203-Q1 Automotive Grade, -16 V to +80 V, Low- or High-Side, High-Speed, Voltage Output Current Shunt Monitor With Dual Comparators and Reference

#### 1 Features

- Qualified for Automotive Applications
- Current Sense Amplifier
  - Common-Mode Range: –16 V to +80 V
  - Accuracy: 3.5% (Maximum) Over Temperature
  - Bandwidth: 500 kHz
  - Gain: 20 V/V
- Integrated Dual Comparators:
  - Comparator 1 With Latch
  - Comparator 2 With Optional Delay
- Quiescent Current: 1.8 mA
- Latch-Up Performance Meets 100 mA Per AEC-Q100, Level I
- Packages: TSSOP-14

## 2 Applications

- Electric Power Steering (EPS) Systems
- Body Control Modules
- Brake Systems
- Electronic Stability Control (ESC) Systems

## 3 Description

The INA203-Q1 is a unidirectional current-shunt monitor (also called a current sense amplifier) with voltage output, dual comparators, and voltage reference. The INA203-Q1 can sense drops across shunts at common-mode voltages from -16 V to +80 V. The INA203-Q1 is available with 20-V/V gain with up to 500-kHz bandwidth.

The INA203-Q1 incorporates two open-drain comparators with internal 0.6-V references and also provides a 1.2-V reference output. The comparator references can be overridden by external inputs. Comparator 1 includes a latching capability, and Comparator 2 has a user-programmable delay.

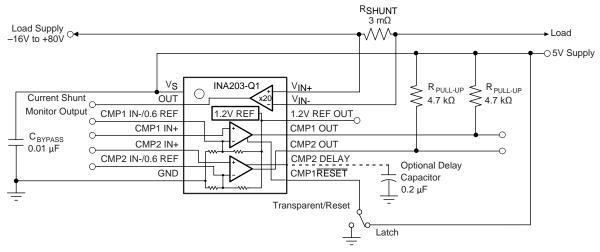
The INA203-Q1 operates from a single 2.7 V to 18 V supply. It is specified over the extended operating temperature range of -40°C to +125°C.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
INA203-Q1	TSSOP (14)	5.00 mm × 4.40 mm

 For all available packages, see the orderable addendum at the end of the data sheet.

#### **Basic Connections Schematic**



Copyright © 2016, Texas Instruments Incorporated



## **Table of Contents**

1	Features 1		8.1 Overview	
2	Applications 1		8.2 Functional Block Diagram	12
3	Description 1		8.3 Feature Description	12
4	Revision History2		8.4 Device Functional Modes	14
5	Device Comparison Table	9	Application and Implementation	15
6	Pin Configuration and Functions		9.1 Application Information	15
7	_		9.2 Typical Applications	19
′	Specifications	10	Power Supply Recommendations	21
	7.1 Absolute Maximum Ratings	11	Layout	
	7.2 ESD Ratings		11.1 Layout Guidelines	
	7.3 Recommended Operating Conditions		11.2 Layout Example	
	7.5 Electrical Characteristics: Current-Shunt Monitor 5	12	Device and Documentation Support	
	7.6 Electrical Characteristics: Comparator		12.1 Community Resources	
	7.7 Electrical Characteristics: Reference		12.2 Trademarks	22
	7.8 Electrical Characteristics: General		12.3 Electrostatic Discharge Caution	22
	7.9 Typical Characteristics		12.4 Glossary	
8	Detailed Description	13	Mechanical, Packaging, and Orderable Information	22

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

C	hanges from Original (December 2010) to Revision A	Page
•	Updated data sheet title, Features, Applications, and Description	1
•	Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, Mechanical, Packaging, and Orderable Information section, Pin Configuration and Functions section, Recommended Operating Conditions Table, and Thermal Information Table	1
•	Added Device Comparison Table	3
•	Changed V+ to V <sub>S</sub> throughout	4
•	Changed MAX value 18 to (V <sub>S</sub> ) + 0.3 for Comparator output pins	4
•	Changed MAX value 10 to (V <sub>S</sub> ) up to 10 for 1.2-V REF and CMP2 DELAY pins	4
•	Changed pin names in Absolute Maximum Ratings to show correct names	4
•	Added Operating Temperature to Absolute Maximum Ratings table	4
•	Changed CMP2 IN- to CMP2 IN+ in Electrical Characteristics: Current-Shunt Monitor condition statement	5
•	Changed CMP2 IN- to CMP2 IN+ in Electrical Characteristics: General condition statement	7
•	Updated Overview section	12
•	Deleted 10-pin device image	12
•	Changed text from "RFILT – 3%" to "RFILT + 3%" in 2nd paragraph of Input Filtering section	16
•	Changed Figure 35 caption	16

Submit Documentation Feedback

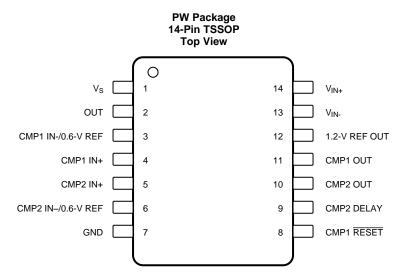


## 5 Device Comparison Table

**Table 1. Related Products** 

PRODUCT	DESCRIPTION
INA200-Q1	Single comparator alternative to the INA203's dual comparators
INA193A-Q1	Same amplifier performance without the comparators integrated
INA282-Q1	High-accuracy, high common-mode capable current sense amplifier
INA300-Q1	36-V overcurrent protection comparator
INA301	High-accuracy, high slew-rate current sense amplifier with integrated high-speed comparator optimized for overcurrent protection.

## 6 Pin Configuration and Functions



**Pin Functions** 

	PIN		DESCRIPTION	
NO.	NAME	I/O	DESCRIPTION	
1	V <sub>S</sub>	I	Power supply	
2	OUT	0	Output voltage	
3	CMP1 IN-/0.6-V REF	I	Comparator 1 negative input, can be used to override the internal 0.6-V reference	
4	CMP1 IN+	I	Comparator 1 positive input	
5	CMP2 IN+	1	Comparator 2 positive input	
6	CMP2 IN-/0.6-V REF	1	Comparator 2 negative input, can be used to override the internal 0.6-V reference	
7	GND	I	Ground	
8	CMP1 RESET	I	Comparator 1 ouput reset, active low	
9	CMP2 DELAY	I	Connect an optional capacitor to adjust comparator 2 delay	
10	CMP2 OUT	0	Comparator 2 output	
11	CMP1 OUT	0	Comparator 1 output	
12	1.2-V REF OUT	0	1.2-V reference output	
13	V <sub>IN</sub> _	I	Amplifier Negative Input. Connect to shunt low side	
14	V <sub>IN+</sub>	I	Amplifier Positive Input. Connect to shunt high side	



## 7 Specifications

## 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
Supply voltage	V <sub>S</sub>		18	V
Current-shunt monitor analog	Differential (V <sub>IN+</sub> ) – (V <sub>IN</sub> –)	-18	18	V
inputs, V <sub>IN+</sub> and V <sub>IN-</sub>	Common-mode	-16	80	V
Comparator analog input	CMP1 IN+, CMP1 IN-/0.6-V REF, CMP2 IN+, CMP2 IN-/0.6-V REF	GND - 0.3	$(V_S) + 0.3$	V
Comparator reset	CMP1 RESET	GND - 0.3	$(V_S) + 0.3$	
Analog output	OUT	GND - 0.3	$(V_S) + 0.3$	V
Comparator output	CMP1 OUT, CMP2 OUT	GND - 0.3	$(V_S) + 0.3$	V
1.2-V REF and CMP2 DELAY pir	ns	GND - 0.3	(V <sub>S</sub> ) up to 10	V
Input current into any pin			5	mA
Operating temperature		-55	150	°C
Junction temperature			150	°C
Storage temperature, T <sub>stg</sub>		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### 7.2 ESD Ratings

			VALUE	UNIT
\/	Floatroototic discharge	Human-body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±2000	V
V <sub>(ESD)</sub>	Electrostatic discharge	Charged-device model (CDM), per AEC Q100-011	±500	V

<sup>(1)</sup> AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

## 7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
$V_{CM}$	Common-mode input voltage	-16	12	80	V
V <sub>S</sub>	Operating supply voltage	2.7	12	18	V
T <sub>A</sub>	Operating free-air temperature	-40	25	125	°C

#### 7.4 Thermal Information

		INA203-Q1	
	THERMAL METRIC <sup>(1)</sup>	PW (TSSOP)	UNIT
		14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	112.6	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	37.2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	55.4	°C/W
ΨЈТ	Junction-to-top characterization parameter	2.7	°C/W
ΨЈВ	Junction-to-board characterization parameter	54.7	°C/W
R <sub>0JC(bot)</sub>	Junction-to-case (bottom) thermal resistance	150	°C/W

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPRA953.



## 7.5 Electrical Characteristics: Current-Shunt Monitor

At  $T_A$  = 25°C,  $V_S$  = 12 V,  $V_{CM}$  = 12 V,  $V_{SENSE}$  = 100 mV,  $R_L$  = 10 k $\Omega$  to GND,  $R_{PULL-UP}$  = 5.1 k $\Omega$  each connected from CMP1 OUT and CMP2 OUT to  $V_S$ , and CMP1 IN+ = 1 V and CMP2 IN+ = GND, unless otherwise noted.

	PARAMETER	TEST CONI	DITIONS	MIN	TYP	MAX	UNIT
INPUT						-	
V <sub>SENSE</sub>	Full-scale sense input voltage	$V_{SENSE} = V_{IN+} - V_{IN-}$			0.15	(V <sub>S</sub> - 0.25)/Gain	V
V <sub>CM</sub>	Common-mode input range	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		-16		80	V
CMRR	Common-mode rejection ratio	$V_{CM} = -16 \text{ V to } +80 \text{ V}$		80	100		dB
	•	V <sub>CM</sub> = 12 V to 80 V	T <sub>A</sub> = 25°C to 125°C	100	123		dB
	Over temperature	$T_A = -40$ °C to +25°C	1	90	100		dB
					±0.5	±2.5	mV
Vos	Offset voltage, RTI <sup>(1)</sup>	T <sub>A</sub> = 25°C to 125°C				±3	mV
		$T_A = -40$ °C to +25°C				±3.5	mV
dV <sub>OS</sub> /dT	Versus temperature	T <sub>MIN</sub> to T <sub>MAX</sub>	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		5		μV/°C
PSR	Versus power supply	V <sub>OUT</sub> = 2 V, V <sub>CM</sub> = +18 V	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		2.5	100	μV/V
I <sub>B</sub>	Input bias current, V <sub>IN</sub> - Pin	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	1		±9	±16	μA
OUTPUT	Γ (V <sub>SENSE</sub> ≥ 20 mV)					<u> </u>	
G	Gain				20		V/V
	Gain error	V <sub>SENSE</sub> = 20 mV to 100 mV			±0.2%	±1%	
	Over temperature	V <sub>SENSE</sub> = 20 mV to 100 mV	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			±2%	
	Total output error <sup>(2)</sup>	V <sub>SENSE</sub> = 120 mV, V <sub>S</sub> = +16 V			±0.75%	±2.2%	
	Over temperature	V <sub>SENSE</sub> = 120 mV, V <sub>S</sub> = +16 V	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			±3.5%	
	Nonlinearity error <sup>(3)</sup>	V <sub>SENSE</sub> = 20 mV to 100 mV			±0.002%		
Ro	Output impedance, Pin 2				1.5		Ω
	Maximum capacitive load	No sustained oscillation			10		nF
OUTPUT	Γ (V <sub>SENSE</sub> < 20 mV) <sup>(4)</sup>						
	<u> </u>	-16 V ≤ V <sub>CM</sub> < 0 V			300		mV
V <sub>OUT</sub>	Output voltage	$0 \text{ V} \le \text{V}_{\text{CM}} \le \text{V}_{\text{S}}, \text{V}_{\text{S}} = 5 \text{ V}$				0.4	V
		V <sub>S</sub> < V <sub>CM</sub> ≤ 80 V			300		mV
VOLTAG	SE OUTPUT <sup>(5)</sup>	1 1					
	Output swing to the positive rail	V <sub>IN-</sub> = 11 V, V <sub>IN+</sub> = 12 V	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		(V <sub>S</sub> ) - 0.15	$(V_S) - 0.25$	V
	Output Swing to GND <sup>(6)</sup>	$V_{IN-} = 0 \text{ V}, V_{IN+} = -0.5 \text{ V}$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	(V <sub>0</sub>	<sub>SND</sub> ) + 0.004	$(V_{GND}) + 0.05$	V
FREQUE	ENCY RESPONSE	1				<u> </u>	
BW	Bandwidth	C <sub>LOAD</sub> = 5 pF			500		kHz
	Phase margin	C <sub>LOAD</sub> < 10 nF			40		Degrees
SR	Slew rate				1		V/µs
	Settling time (1%)	$V_{SENSE} = 10 \text{ mV}_{PP} \text{ to } 100 \text{ mV}_{F}$ $C_{LOAD} = 5 \text{ pF}$	PP,		2		μs
NOISE, I	RTI	•				<u> </u>	
	Output Voltage Noise Density				40		nV/√ <del>Hz</del>

<sup>(1)</sup> Offset is extrapolated from measurements of the output at 20 mV and 100 mV V<sub>SENSE</sub>.

<sup>(2)</sup> Total output error includes effects of gain error and V<sub>OS</sub>.

<sup>(3)</sup> Linearity is best fit to a straight line.

<sup>(4)</sup> For details on this region of operation, see the Accuracy Variations section.

<sup>(5)</sup> See Typical Characteristics curve Positive Output Voltage Swing vs Output Current (Figure 8).

<sup>6)</sup> Specified by design; not production tested.



## 7.6 Electrical Characteristics: Comparator

At  $T_A$  = +25°C,  $V_S$  = +12 V,  $V_{CM}$  = +12 V,  $V_{SENSE}$  = 100 mV,  $R_L$  = 10 k $\Omega$  to GND, and  $R_{PULL-UP}$  = 5.1 k $\Omega$  each connected from CMP1 OUT and CMP2 OUT to  $V_S$ , unless otherwise noted.

OFFSET VOLTAGE         Offset voltage       Comparator common-mode voltage = threshold voltage         Offset voltage drift, comparator 1 $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ Offset voltage drift, comparator 2 $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ Threshold       Rising Edge on Non-Inverting input, $T_A = +25^{\circ}\text{C}$ Over temperature $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ Hysteresis(1), CMP1 $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ Hysteresis(1), CMP2 $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ INPUT BIAS CURRENT(2)       TA = $-40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ CMP1 IN+, CMP2 IN+       TA = $-40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ INPUT IMPEDANCE       Pins 3 and 6         INPUT RANGE       CMP1 IN+ and CMP2 IN+         Pins 3 and 6 (3)       Pins 3 and 6 (3)	500	2 ±2		
Offset voltage drift, comparator 1 $T_A = -40^{\circ}\text{C}$ to +125°C  Offset voltage drift, comparator 2 $T_A = -40^{\circ}\text{C}$ to +125°C  Threshold Rising Edge on Non-Inverting input, $T_A = +25^{\circ}\text{C}$ Over temperature $T_A = -40^{\circ}\text{C}$ to +125°C  Hysteresis <sup>(1)</sup> , CMP1 $T_A = -40^{\circ}\text{C}$ to +85°C  Hysteresis <sup>(1)</sup> , CMP2 $T_A = -40^{\circ}\text{C}$ to +85°C  INPUT BIAS CURRENT <sup>(2)</sup> CMP1 IN+, CMP2 IN+  Over temperature $T_A = -40^{\circ}\text{C}$ to +125°C  INPUT IMPEDANCE  Pins 3 and 6  INPUT RANGE  CMP1 IN+ and CMP2 IN+	500			
Offset voltage drift, comparator 2 $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ Threshold Rising Edge on Non-Inverting input, $T_A = +25^{\circ}\text{C}$ Over temperature $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ Hysteresis <sup>(1)</sup> , CMP1 $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ Hysteresis <sup>(1)</sup> , CMP2 $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ INPUT BIAS CURRENT <sup>(2)</sup> CMP1 IN+, CMP2 IN+  Over temperature $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ INPUT IMPEDANCE  Pins 3 and 6  INPUT RANGE  CMP1 IN+ and CMP2 IN+	500	±2		mV
Threshold Rising Edge on Non-Inverting input, $T_A = +25^{\circ}C$ Over temperature $T_A = -40^{\circ}C$ to $+125^{\circ}C$ Hysteresis <sup>(1)</sup> , CMP1 $T_A = -40^{\circ}C$ to $+85^{\circ}C$ Hysteresis <sup>(1)</sup> , CMP2 $T_A = -40^{\circ}C$ to $+85^{\circ}C$ INPUT BIAS CURRENT <sup>(2)</sup> CMP1 IN+, CMP2 IN+  Over temperature $T_A = -40^{\circ}C$ to $+125^{\circ}C$ INPUT IMPEDANCE  Pins 3 and 6  INPUT RANGE  CMP1 IN+ and CMP2 IN+	500			μV/°C
Over temperature $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ Hysteresis <sup>(1)</sup> , CMP1 $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ Hysteresis <sup>(1)</sup> , CMP2 $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ INPUT BIAS CURRENT <sup>(2)</sup> CMP1 IN+, CMP2 IN+  Over temperature $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ INPUT IMPEDANCE  Pins 3 and 6  INPUT RANGE  CMP1 IN+ and CMP2 IN+	500	5.4		μV/°C
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	590	608	620	mV
Hysteresis (1), CMP2	586	-	625	mV
INPUT BIAS CURRENT <sup>(2)</sup> CMP1 IN+, CMP2 IN+  Over temperature  T <sub>A</sub> = -40°C to +125°C  INPUT IMPEDANCE  Pins 3 and 6  INPUT RANGE  CMP1 IN+ and CMP2 IN+		-8		mV
CMP1 IN+, CMP2 IN+  Over temperature		8		mV
Over temperature T <sub>A</sub> = -40°C to +125°C  INPUT IMPEDANCE  Pins 3 and 6  INPUT RANGE  CMP1 IN+ and CMP2 IN+				
INPUT IMPEDANCE Pins 3 and 6 INPUT RANGE CMP1 IN+ and CMP2 IN+		0.005	10	nA
Pins 3 and 6  INPUT RANGE  CMP1 IN+ and CMP2 IN+		-	15	nA
INPUT RANGE  CMP1 IN+ and CMP2 IN+				
CMP1 IN+ and CMP2 IN+		10		kΩ
Pins 3 and 6 <sup>(3)</sup>	0 V	/ to V <sub>S</sub> – 1.5 V		V
1 ino o dila o	0 V	/ to V <sub>S</sub> – 1.5 V		V
OUTPUT				
Large-signal differential voltage gain CMP V <sub>OUT</sub> 1 V to 4 V, R <sub>L</sub> ≥ 15 kΩ connected to 5 V		200		V/mV
High-level output current $V_{ID} = 0.4 \text{ V}, V_{OH} = V_{S}$		0.0001	1	μA
Low-level output voltage $V_{ID} = -0.6 \text{ V}, I_{OL} = 2.35 \text{ mA}$		220	300	mV
RESPONSE TIME <sup>(4)</sup>				
Comparator 1 R <sub>L</sub> to 5 V, C <sub>L</sub> = 15 pF, 100 mV input step with 5 mV overdrive	re l	1.3		μs
Comparator 2 R <sub>L</sub> to 5 V, C <sub>L</sub> = 15 pF, 100 mV input step with 5 mV overdrive C <sub>DELAY</sub> pin open	re,	1.3		μs
RESET	*			
RESET threshold <sup>(5)</sup>		1.1		V
Logic input impedance		2		МΩ
Minimum RESET pulse width		1.5		μs
RESET propagation delay		3		μs
Comparator 2 delay equation <sup>(6)</sup>		$C_{DELAY} = t_D/5$		μF
$t_D$ Comparator 2 delay $C_{DELAY} = 0.1  \mu F$		ODELAY - ID/O		

<sup>(1)</sup> Hysteresis refers to the threshold (the threshold specification applies to a rising edge of a noninverting input) of a falling edge on the noninverting input of the comparator; refer to Figure 1.

(6) The Comparator 2 delay applies to both rising and falling edges of the comparator output.

Submit Documentation Feedback

Copyright © 2010–2016, Texas Instruments Incorporated

<sup>(2)</sup> Specified by design; not production tested.

<sup>(3)</sup> See the Comparator Maximum Input Voltage Range section.

<sup>(4)</sup> The comparator response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

<sup>(5)</sup> The CMP1 RESET input has an internal 2 MΩ (typical) pull-down. Leaving the CMP1 RESET open results in a LOW state, with transparent comparator operation.



#### 7.7 Electrical Characteristics: Reference

At  $T_A$  = +25°C,  $V_S$  = +12 V,  $V_{CM}$  = +12 V,  $V_{SENSE}$  = 100 mV,  $R_L$  = 10 k $\Omega$  to GND, and  $R_{PULL-UP}$  = 5.1 k $\Omega$  each connected from CMP1 OUT and CMP2 OUT to  $V_S$ , unless otherwise noted.

	PARAMETER	TEST C	ONDITIONS	MIN	TYP	MAX	UNIT
REFERENCE	VOLTAGE	-					
	1.2 V <sub>REFOUT</sub> output voltage			1.188	1.2	1.212	V
dV <sub>OUT</sub> /dT	Reference drift <sup>(1)</sup>	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$			40	100	ppm/°C
0.6 V <sub>REF</sub>	Output voltage (Pins 3 and 6)				0.6		V
dV <sub>OUT</sub> /dT	Reference drift <sup>(1)</sup>	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$			40	100	ppm/°C
LOAD REGUL	ATION						
-1\/ /-11	Sourcing	0.774	V <sub>REFOUT</sub> – 1.2 V		0.4	2	mV/mA
dV <sub>OUT</sub> /dI <sub>LOAD</sub>	Sinking	$0 \text{ mA} < I_{SINK} < 0.5 \text{ mA}$	0 mA < I <sub>SOURCE</sub> < 0.5 mA		0.4		mV/mA
LOAD CURRE	ENT						
I <sub>LOAD</sub>					1		mA
LINE REGULA	ATION						
dV <sub>OUT</sub> /dV <sub>S</sub>		2.7 V < V <sub>S</sub> < 18 V			30		μV/V
CAPACITIVE	LOAD						
	Reference output maximum capacitive load	No sustained oscillation	s		10		nF
OUTPUT IMP	EDANCE						
	Pins 3 and 6				10		kΩ

<sup>(1)</sup> Specified by design; not production tested.

#### 7.8 Electrical Characteristics: General

All specifications at  $T_A$  = +25°C,  $V_S$  = +12 V,  $V_{CM}$  = +12 V,  $V_{SENSE}$  = 100 mV,  $R_L$  = 10 k $\Omega$  to GND,  $R_{PULL-UP}$  = 5.1 k $\Omega$  each connected from CMP1 OUT and CMP2 OUT to  $V_S$ , and CMP1 IN+ = 1 V and CMP2 IN+ = GND, unless otherwise noted.

	GENERAL PARAMETERS	CONDI	TIONS	MIN	TYP	MAX	UNIT			
POWER SUPPLY										
$V_S$	Operating Power Supply	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		2.7		18	V			
$I_Q$	Quiescent current	V <sub>OUT</sub> = 2 V			1.8	2.2	mA			
	Over temperature	V <sub>SENSE</sub> = 0 mV	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			2.8	mA			
	Comparator power-on reset threshold (1)				1.5		V			

(1) The INA203-Q1 is designed to power-up with the comparator in a defined reset state as long as CMP1 RESET is open or grounded. The comparator will be in reset as long as the power supply is below the voltage shown here. The comparator assumes a state based on the comparator input above this supply voltage. If CMP1 RESET is high at power-up, the comparator output comes up high and requires a reset to assume a low state, if appropriate.

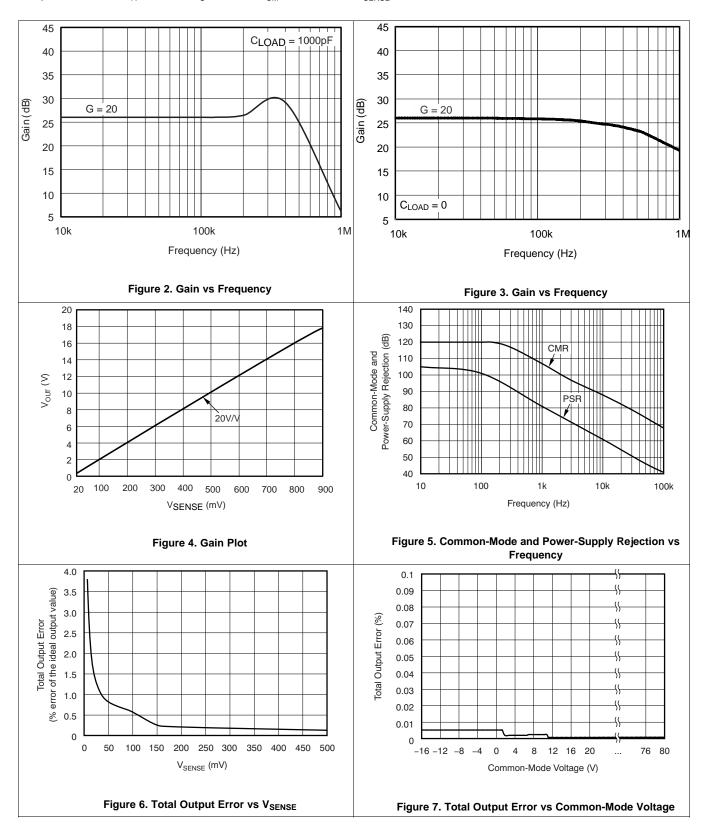


Figure 1. Comparator Hysteresis

## TEXAS INSTRUMENTS

## 7.9 Typical Characteristics

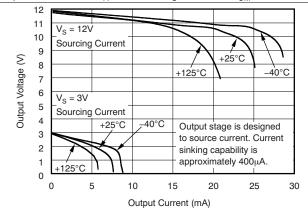
All specifications at  $T_A = +25$ °C,  $V_S = +12$  V,  $V_{CM} = +12$  V, and  $V_{SENSE} = 100$  mV, unless otherwise noted.





## **Typical Characteristics (continued)**

All specifications at  $T_A = +25$ °C,  $V_S = +12$  V,  $V_{CM} = +12$  V, and  $V_{SENSE} = 100$  mV, unless otherwise noted.



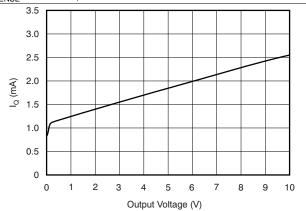
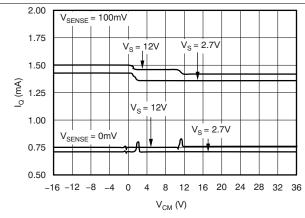


Figure 8. Positive Output Voltage Swing vs Output Current

Figure 9. Quiescent Current vs Output Voltage



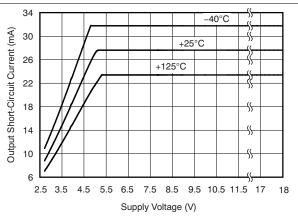
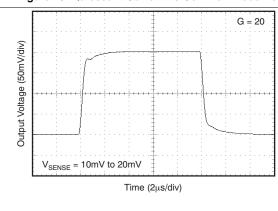


Figure 10. Quiescent Current vs Common-Mode Voltage

Figure 11. Output Short-Circuit Current vs Supply Voltage



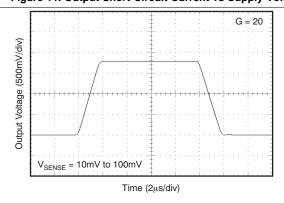


Figure 12. Step Response

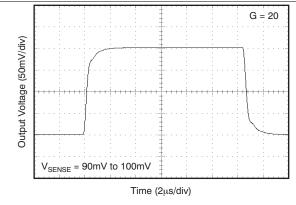
Figure 13. Step Response

Submit Documentation Feedback Copyright © 2010-2016, Texas Instruments Incorporated

## TEXAS INSTRUMENTS

## **Typical Characteristics (continued)**

All specifications at  $T_A = +25$ °C,  $V_S = +12$  V,  $V_{CM} = +12$  V, and  $V_{SENSE} = 100$  mV, unless otherwise noted.



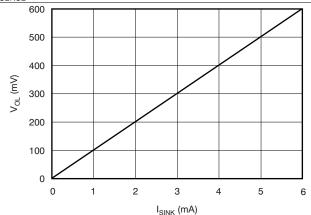
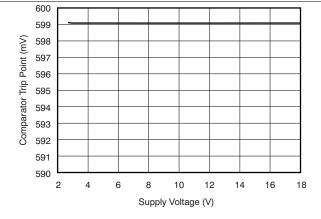


Figure 14. Step Response

Step Response Figure 15. Comparator V<sub>OL</sub> vs I<sub>SINK</sub>



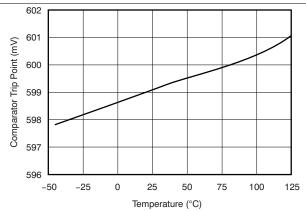
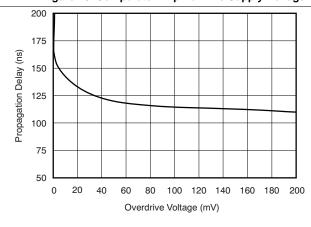


Figure 16. Comparator Trip Point vs Supply Voltage

Figure 17. Comparator Trip Point vs Temperature



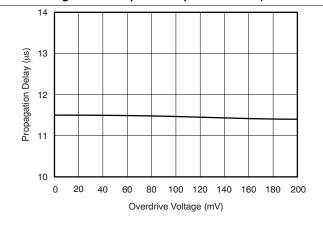


Figure 18. Comparator 1 Propagation Delay vs Overdrive Voltage

Figure 19. Comparator 2 Propagation Delay vs Overdrive Voltage

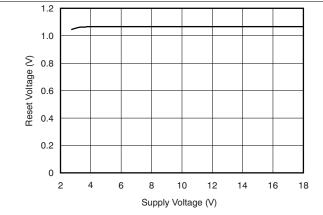
Submit Documentation Feedback

Copyright © 2010–2016, Texas Instruments Incorporated



## **Typical Characteristics (continued)**

All specifications at  $T_A$  = +25°C,  $V_S$  = +12 V,  $V_{CM}$  = +12 V, and  $V_{SENSE}$  = 100 mV, unless otherwise noted.



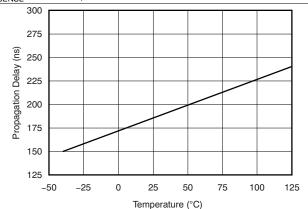
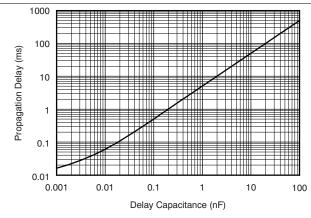


Figure 20. Comparator Reset Voltage vs supply Voltage

Figure 21. Comparator 1 Propagation Delay vs Temperature



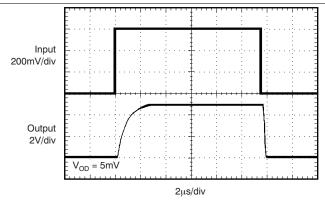
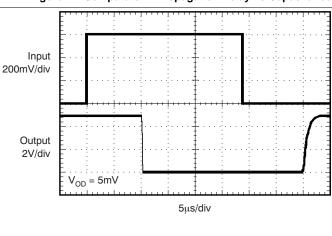


Figure 22. Comparator 2 Propagation Delay vs Capacitance

Figure 23. Comparator 1 Propagation Delay



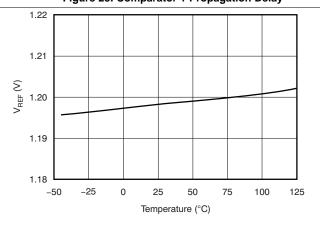


Figure 24. Comparator 2 Propagation Delay

Figure 25. Reference Voltage vs Temperature

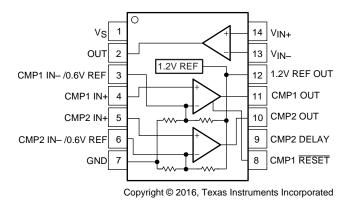


## 8 Detailed Description

#### 8.1 Overview

The INA203-Q1 device is a unidirectional voltage output current-sense amplifier with dual comparators and voltage reference. The INA203-Q1 operates over a wide range of common-mode voltage (–16 V to +80 V) and incorporates two open-drain comparators with internal 0.6-V references. Comparator 1 includes a latching capability, and Comparator 2 has a user-programmable delay. The device also incorporates a 1.2-V reference output.

#### 8.2 Functional Block Diagram



#### 8.3 Feature Description

#### 8.3.1 Comparator

The INA203-Q1 incorporates two open-drain comparators. These comparators typically have 2 mV of offset and a 1.3-µs (typical) response time. The output of Comparator 1 latches and is reset through the CMP1 RESET pin, as shown in Figure 26.

The INA203-Q1 device includes additional features for comparator functions. The comparator reference voltage of both Comparator 1 and Comparator 2 can be overridden by external inputs for increased design flexibility. Comparator 2 has a programmable delay.

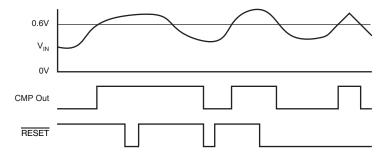


Figure 26. Comparator Latching Capability

## 8.3.2 Comparator Delay

The Comparator 2 programmable delay is controlled by a capacitor connected to the CMP2 Delay Pin; see Figure 30. The capacitor value (in  $\mu$ F) is selected by using Equation 1:

$$C_{DELAY} (in \mu F) = \frac{t_D}{5}$$
 (1)

A simplified version of the delay circuit for Comparator 2 is shown in Figure 27. The delay comparator consists of two comparator stages with the delay between them.



#### Feature Description (continued)

#### **NOTE**

I1 and I2 cannot be turned on simultaneously; I1 corresponds to a U1 low output and I2 corresponds to a U1 high output.

Using an initial assumption that the U1 output is low, I1 is on, then U2 +IN is zero. If U1 goes high, I2 supplies 120 nA to  $C_{DELAY}$ . The voltage at U2 +IN begins to ramp toward a 0.6-V threshold. When the voltage crosses this threshold, the U2 output goes high while the voltage at U2 +IN continues to ramp up to a maximum of 1.2 V when given sufficient time (twice the value of the delay specified for  $C_{DELAY}$ ). This entire sequence is reversed when the comparator outputs go low, so that returning to low exhibits the same delay.

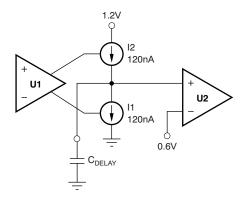


Figure 27. Simplified Model of The Comparator 2 Delay Circuit

It is important to note the behavior of the Comparator 2 when the events at the inputs occur more rapidly than the set delay timeout. For example, when the U1 output goes high (turning on I2), but returns low (turning I1 back on) prior to reaching the 0.6 V transition for U2. The voltage at U2 +IN ramps back down at a rate determined by the value of  $C_{\text{DFLAY}}$ , and only returns to zero if given sufficient time.

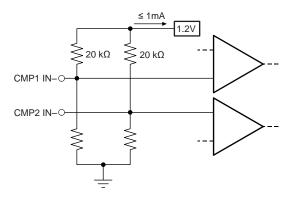
In essence, when analyzing Comparator 2 for behavior with events more rapid than its delay setting, use the model shown in Figure 27.

#### 8.3.3 Comparator Maximum Input Voltage Range

The maximum voltage at the comparator input for normal operation is up to  $(V_S)-1.5$  V. There are special considerations when overdriving the reference inputs (pins 3 and 6). Driving either or both inputs high enough to drive 1 mA back into the reference introduces errors into the reference. Figure 28 shows the basic input structure. A general guideline is to limit the voltage on both inputs to a total of 20 V. The exact limit depends on the available voltage and whether either or both inputs are subject to the large voltage. When making this determination, consider the 20 k $\Omega$  from each input back to the comparator. Figure 29 shows the maximum input voltage that avoids creating a reference error when driving both inputs (an equivalent resistance back into the reference of 10 k $\Omega$ ).



#### **Feature Description (continued)**



Copyright © 2016, Texas Instruments Incorporated

Figure 28. Limit Current Into Reference ≤ 1 mA

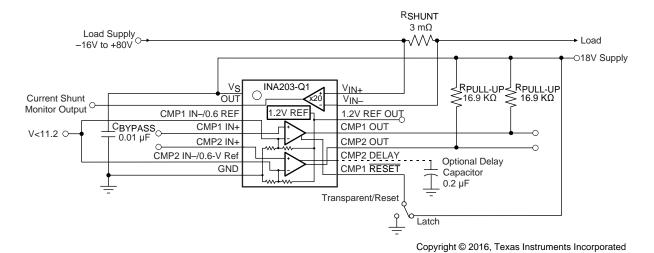


Figure 29. Overdriving Comparator Inputs Without Generating a Reference Error

#### 8.3.4 Reference

The INA203-Q1 include an internal voltage reference that has a load regulation of 0.4 mV/mA (typical), and not more than 100 ppm/°C of drift. The device allows external access to reference voltages, where voltages of 1.2 V and 0.6 V are both available. Output current versus output voltage is illustrated in the *Typical Characteristics* section.

#### 8.3.5 Output Voltage Range

The output of the INA203-Q1 is accurate within the output voltage swing range set by the power-supply pin,  $V_S$ . Given the device gain of 20, where a 250 mV full-scale input from the shunt resistor requires an output voltage swing of +5 V, and a power-supply voltage sufficient to achieve +5 V on the output.

#### 8.4 Device Functional Modes

The INA203-Q1 has a single functional mode and is operational when the power-supply voltage is greater than 2.7 V. The common-mode voltage must be between -16 V and +80 V. The maximum power supply voltage for the INA203-Q1 is 18 V.

Product Folder Links: INA203-Q1

Copyright © 2010-2016, Texas Instruments Incorporated



## 9 Application and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

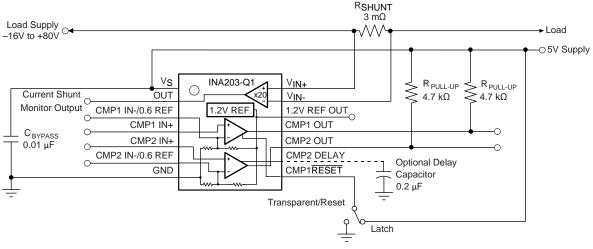
#### 9.1 Application Information

The INA203-Q1 device is designed to enable easy configuration for detecting overcurrent conditions and current monitoring in an application. This device is also incorporate two open-drain comparators with internal 0.6-V references. The comparator references can be overridden by external inputs. Comparator 1 includes a latching capability, and Comparator 2 has a user-programmable delay. The INA203-Q1 also provides a 1.2-V reference output. This device can also be paired with minimum additional devices to create more sophisticated monitoring functional blocks.

#### 9.1.1 Basic Connections

Figure 30 shows the basic connections of the INA203-Q1. Connect the input pins,  $V_{IN+}$  and  $V_{IN-}$ , as closely as possible to the shunt resistor to minimize any resistance in series with the shunt resistance.

Power-supply bypass capacitors are required for stability. Applications with noisy or high-impedance power supplies may require additional decoupling capacitors to reject power-supply noise. Connect bypass capacitors close to the device pins.



Copyright © 2016, Texas Instruments Incorporated

Figure 30. INA203-Q1 Basic Connection

## 9.1.2 Selecting R<sub>SHUNT</sub>

The value chosen for the shunt resistor,  $R_{SHUNT}$ , depends on the application and is a compromise between small-signal accuracy and maximum permissible voltage loss in the measurement line. High values of  $R_{SHUNT}$  provide better accuracy at lower currents by minimizing the effects of offset, while low values of  $R_{SHUNT}$  minimize voltage loss in the supply line. For most applications, best performance is attained with an  $R_{SHUNT}$  value that provides a full-scale shunt voltage range of 50 mV to 100 mV. Maximum input voltage for accurate measurements is  $(V_{SHUNT}-0.25)/Gain$ .



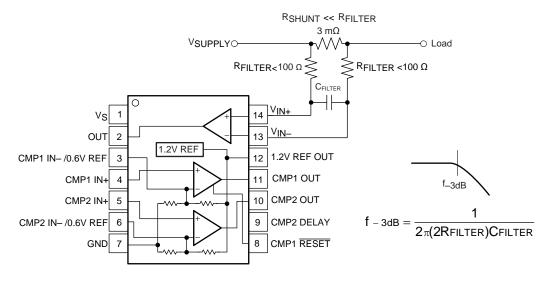
## **Application Information (continued)**

#### 9.1.3 Input Filtering

An obvious and straightforward location for filtering is at the output of the INA203-Q1 series; however, this location negates the advantage of the low output impedance of the internal buffer. The only other option for filtering is at the input pins of the INA203-Q1, which is complicated by the internal 5 k $\Omega$  + 30% input impedance; this configuration is illustrated in Figure 31. Using the lowest possible resistor values minimizes both the initial shift in gain and effects of tolerance. Equation 2 gives the effect on initial gain:

Gain Error % = 
$$100 - \left[100 \times \frac{5k\Omega}{5k\Omega + R_{FILT}}\right]$$
 (2)

To calculate the total effect on gain error, replace the 5-k $\Omega$  term with 5 k $\Omega$  – 30%, (or 3.5 k $\Omega$ ) or 5 k $\Omega$  + 30% (or 6.5 k $\Omega$ ). The tolerance extremes of R<sub>FILT</sub> can also be inserted into the equation. If a pair of 100- $\Omega$  1% resistors are used on the inputs, then the initial gain error will be 1.96%. Worst-case tolerance conditions will always occur at the lower excursion of the internal 5-k $\Omega$  resistor (3.5 k $\Omega$ ), and the higher excursion of R<sub>FILT</sub> + 3% in this case.



Copyright © 2016, Texas Instruments Incorporated

Figure 31. Input Filter

#### **NOTE**

The specified accuracy of the INA203-Q1 must then be combined in addition to these tolerances. While this discussion treated accuracy worst-case conditions by combining the extremes of the resistor values, it is appropriate to use geometric-mean or root-sumsquare calculations to total the effects of accuracy variations.

#### 9.1.4 Accuracy Variations as a Result of V<sub>SENSE</sub> and Common-Mode Voltage

The accuracy of the INA203-Q1 current-shunt monitors is a function of two main variables:  $V_{SENSE}$  ( $V_{IN+} - V_{IN-}$ ) and common-mode voltage,  $V_{CM}$ , relative to the supply voltage,  $V_S$ .  $V_{CM}$  is expressed as ( $V_{IN+} + V_{IN-}$ )/2; however, in practice,  $V_{CM}$  is seen as the voltage at  $V_{IN+}$  because the voltage drop across  $V_{SENSE}$  is usually small.

This section addresses the accuracy of these specific operating regions:

- Normal Case 1: V<sub>SENSE</sub> ≥ 20 mV, V<sub>CM</sub> ≥ V<sub>S</sub>
- Normal Case 2: V<sub>SENSE</sub> ≥ 20 mV, V<sub>CM</sub> < V<sub>S</sub>
- Low V<sub>SENSE</sub> Case 1: V<sub>SENSE</sub> < 20 mV, −16 V ≤ V<sub>CM</sub> < 0</li>
- Low V<sub>SENSE</sub> Case 2: V<sub>SENSE</sub> < 20 mV, 0 V ≤ V<sub>CM</sub> ≤ V<sub>S</sub>
- Low V<sub>SENSE</sub> Case 3: V<sub>SENSE</sub> < 20 mV, V<sub>S</sub> < V<sub>CM</sub> ≤ 80 V

Submit Documentation Feedback

Copyright © 2010–2016, Texas Instruments Incorporated



## **Application Information (continued)**

## 9.1.4.1 Normal Case 1: $V_{SENSE} \ge 20 \text{ mV}$ , $V_{CM} \ge V_{S}$

This region of operation provides the highest accuracy. Here, the input offset voltage is characterized and measured using a two-step method. First, the gain is determined by Equation 3.

$$G = \frac{V_{OUT1} - V_{OUT2}}{100mV - 20mV}$$

where

• V<sub>OUT1</sub> = output voltage with V<sub>SENSE</sub> = 100 mV

• 
$$V_{OUT2}$$
 = output voltage with  $V_{SENSE}$  = 20 mV (3)

Then the offset voltage is measured at  $V_{SENSE} = 100$  mV and referred to the input (RTI) of the current shunt monitor, as shown in Equation 4.

$$V_{OS}RTI \text{ (Referred-To-Input)} = \left[\frac{V_{OUT1}}{G}\right] - 100\text{mV}$$
(4)

In the *Typical Characteristics* section, the *Output Error vs Common-Mode Voltage* curve (Figure 7) shows the highest accuracy for this region of operation. In this plot,  $V_S = 12 \text{ V}$ ; for  $V_{CM} \ge 12 \text{ V}$ , the output error is at its minimum. This case is also used to create the  $V_{SENSE} \ge 20 \text{ mV}$  output specifications in the *Electrical Characteristics* table.

## 9.1.4.2 Normal Case 2: $V_{SENSE} \ge 20 \text{ mV}$ , $V_{CM} < V_{S}$

This region of operation has slightly less accuracy than Normal Case 1 as a result of the common-mode operating area in which the part functions, as seen in the *Output Error vs Common-Mode Voltage* curve (Figure 7). As noted, for this graph  $V_S = 12 \text{ V}$ ; for  $V_{CM} < 12 \text{ V}$ , the output error increases as  $V_{CM}$  becomes less than 12 V, with a typical maximum error of 0.005% at the most negative  $V_{CM} = -16 \text{ V}$ .

#### 9.1.4.3 Low V<sub>SFNSF</sub> Case 1:

 $V_{SENSE}$  < 20 mV, -16 V  $\leq$   $V_{CM}$  < 0; and

Low V<sub>SENSE</sub> Case 3:

 $V_{SENSE} < 20 \text{ mV}, V_S < V_{CM} \le 80 \text{ V}$ 

Although the INA203-Q1 is not designed for accurate operation in either of these regions, some applications are exposed to these conditions; for example, when monitoring power supplies that are switched on and off while V<sub>S</sub> is still applied to the INA203-Q1. It is important to know what the behavior of the devices will be in these regions.

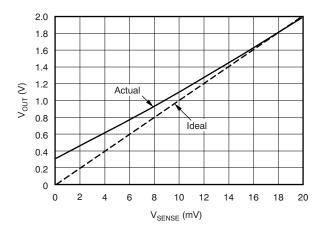
As  $V_{SENSE}$  approaches 0 mV, in these  $V_{CM}$  regions, the device output accuracy degrades. A larger-than-normal offset can appear at the current shunt monitor output with a typical maximum value of  $V_{OUT} = 300$  mV for  $V_{SENSE} = 0$  mV. As  $V_{SENSE}$  approaches 20 mV,  $V_{OUT}$  returns to the expected output value with accuracy as specified in the *Electrical Characteristics*. Figure 32 illustrates this effect (Gain = 100).

Product Folder Links: INA203-Q1

Submit Documentation Feedback

## **STRUMENTS**

#### Application Information (continued)

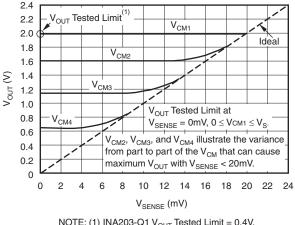


Data taken from INA205, a device of INA20x family with Gain = 100

Figure 32. Example for Low  $V_{SENSE}$  Cases 1 and 3 (Gain = 100)

## 9.1.4.4 Low $V_{SENSE}$ Case 2: $V_{SENSE} < 20 \text{ mV}$ , 0 $V \le V_{CM} \le V_{S}$

This region of operation is the least accurate for the INA203-Q1. To achieve the wide input common-mode voltage range, this device uses two operational amplifiers (Opamp) front ends in parallel. One Opamp front end operates in the positive input common-mode voltage range, and the other in the negative input region. For this case, neither of these two internal amplifiers dominate and overall loop gain is very low. Within this region, Vour approaches voltages close to linear operation levels for Normal Case 2. This deviation from linear operation becomes greatest the closer  $V_{SENSE}$  approaches 0 V. Within this region, as  $V_{SENSE}$  approaches 20 mV, device operation is closer to that described by Normal Case 2. Figure 33 illustrates this behavior. The  $V_{OUT}$  maximum peak for this case is tested by maintaining a constant  $V_S$ , setting  $V_{SENSE} = 0$  mV, and sweeping  $V_{CM}$  from 0 V to Vs. The exact V<sub>CM</sub> at which V<sub>OUT</sub> peaks during this test varies from part to part, but the V<sub>OUT</sub> maximum peak is tested to be less than the specified V<sub>OUT</sub> Tested Limit.



NOTE: (1) INA203-Q1  $V_{OUT}$  Tested Limit = 0.4V.

Data taken from INA205, a device of INA20x family with Gain = 100

Figure 33. Example for Low  $V_{SENSE}$  Case 2 (Gain = 100)



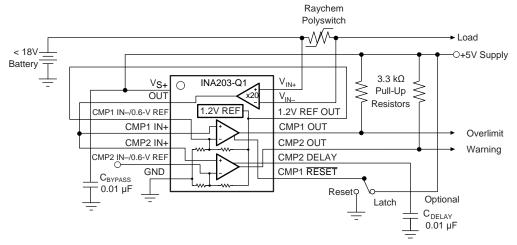
#### Application Information (continued)

#### 9.1.5 Transient Protection

The -16 V to +80 V common-mode range of the INA203-Q1 is ideal for withstanding automotive fault conditions ranging from 12-V battery reversal up to 80-V transients, since no additional protective components are needed up to those levels. In the event that the INA203-Q1 is exposed to transients on the inputs in excess of their ratings, then external transient absorption with semiconductor transient absorbers (zeners or *Transzorbs*) are necessary. Use of metal oxide varistors (MOVs) or video disk recorders (VDRs) is not recommended except when they are used in addition to a semiconductor transient absorber. Select the transient absorber such that it will never allow the INA203-Q1 to be exposed to transients greater than 80 V (that is, allow for transient absorber tolerance, as well as additional voltage because of transient absorber dynamic impedance). Despite the use of internal zener-type ESD protection, the INA203-Q1 does not lend itself to using external resistors in series with the inputs because the internal gain resistors can vary up to ±30% but are closely matched. (If gain accuracy is not important, then resistors can be added in series with the INA203-Q1 inputs with two equal resistors on each input.)

## 9.2 Typical Applications

#### 9.2.1 Polyswitch Warning and Fault Detection Circuit



Copyright © 2016, Texas Instruments Incorporated

Figure 34. Polyswitch Warning and Fault Detection Circuit Schematic

#### 9.2.1.1 Design Requirements

The device measures current through a resistive shunt with current flowing in one direction, thus enabling detection of an overlimit or warning event only when the differential input voltage exceeds the corresponding threshold limits. When the current reaches the warning limit of 0.6 V, the output of CMP2 will transition high indicating a warning condition. When the current further increases to or past the overlimit limit of 1.2 V, the output of CMP1 will transition high indicating an overlimit condition. Optional  $C_{\text{DELAY}}$  can be sized to add delay to CMP2.

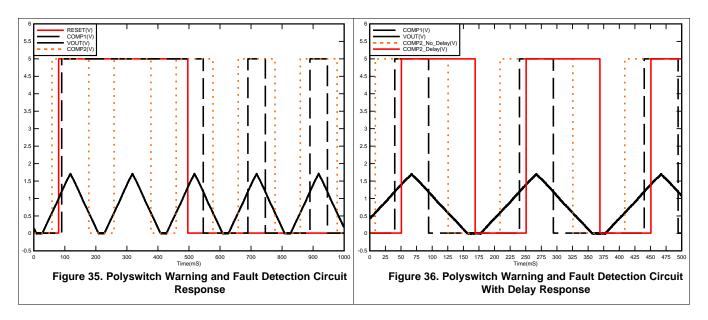
#### 9.2.1.2 Detailed Design Procedure

Figure 34 shows the basic connections of the device. The input terminals,  $V_{IN+}$  and  $V_{IN-}$ , should be connected as close as possible to the current-sensing resistor or polymeric switch to minimize any resistance in series with the shunt resistance. Additional resistance between the current-sensing resistor and input terminals can result in errors in the measurement. When input current flows through this external input resistance, the voltage developed across the shunt resistor can differ from the voltage reaching the input terminals.



## **Typical Applications (continued)**

## 9.2.1.3 Application Curves



## 9.2.2 Lead-Acid Battery Protection Circuit

See Figure 37 for a protection scheme using INA203-Q1 for a lead-acid battery application.

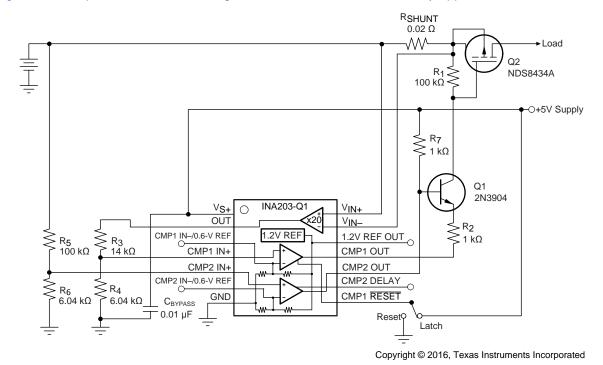


Figure 37. Lead-Acid Battery Protection Circuit Schematic

Submit Documentation Feedback



## 10 Power Supply Recommendations

The input circuitry of the INA203-Q1 can accurately measure beyond the power-supply voltage,  $V_S$ . For example, the  $V_S$  power supply can be 5 V, whereas the load power-supply voltage is up to 80 V. The output voltage range of the OUT terminal, however, is limited by the voltages on the power-supply pin.

## 11 Layout

## 11.1 Layout Guidelines

- Connect the input pins to the sensing resistor using a Kelvin or 4-wire connection. This connection technique
  ensures that only the current-sensing resistor impedance is detected between the input pins. Poor routing of
  the current-sensing resistor commonly results in additional resistance present between the input pins. Given
  the very low ohmic value of the current resistor, any additional high-current carrying impedance can cause
  significant measurement errors.
- The power-supply bypass capacitor should be placed as closely as possible to the supply and ground pins. TI
  recommends the value of this bypass capacitor is 0.1 μF. Additional decoupling capacitance can be added to
  compensate for noisy or high-impedance power supplies.

#### 11.2 Layout Example

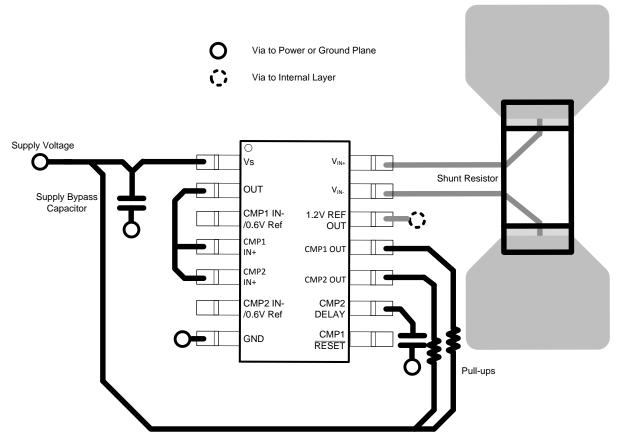


Figure 38. Layout Recommendation



## 12 Device and Documentation Support

#### 12.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

#### 12.2 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

#### 12.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## 12.4 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



## PACKAGE OPTION ADDENDUM

9-Feb-2016

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
INA203AQPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I203AQ	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



## **PACKAGE OPTION ADDENDUM**

9-Feb-2016

#### OTHER QUALIFIED VERSIONS OF INA203-Q1:

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

## PACKAGE MATERIALS INFORMATION

www.ti.com 9-Feb-2016

## TAPE AND REEL INFORMATION





_		
		Dimension designed to accommodate the component width
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
ı	P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA203AQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 9-Feb-2016



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
INA203AQPWRQ1	TSSOP	PW	14	2000	367.0	367.0	35.0	

PW (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
  - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



## PW (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

#### Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic Security www.ti.com/security logic.ti.com

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID www.ti-rfid.com

OMAP Applications Processors <a href="www.ti.com/omap">www.ti.com/omap</a> TI E2E Community <a href="e2e.ti.com">e2e.ti.com</a>

Wireless Connectivity www.ti.com/wirelessconnectivity